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| Project | **Specification of Sensor Interface for Cyber and Physical World**  <<https://sagroups.ieee.org/2888/> **>** |
| Title | External MOU with Multi-dimensional Images Technology Standardization Forum |
| DCN | **2888-20-0054-00-0000** |
| Date Submitted | **December 23, 2020** |
| Source(s) | Sangkwon Jeong, [ceo@joyfun.kr](mailto:ceo@joyfun.kr) (Joyfun)  HyeonWoo Nam, [hwnam@dongduk.ac.kr](mailto:hwnam@dongduk.ac.kr) (Dongduk Women’s University) |
| Re: |  |
| Abstract | This contribution is MOU letter within IEEE 2888 WG and Multi-dimensional Images Technology Standardization Forum |
| Purpose | External MOU with Multi-dimensional Images Technology Standardization Forum |
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**Request for Establishment of External MOU**   
**between the IEEE 2888 and Multi-dimensional Images Technology Standardization Forum**

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| **Category** | External MOU with IEEE 2888 |
| **MOU Organization** | Multi-dimensional Images Technology Standardization Forum  Web : None  **Contact person**: Prof. HyeonWoo Nam  Company: Dongduk Women’s Univ.  Address: Dongduk Women’s Univ. 60, Hwarang-ro 13gil, Seongbuk-gu, Seoul, 02748, Republic of Korea  Email : [hwnam@dongduk.ac.kr](mailto:hwnam@dongduk.ac.kr) |
| **MOU Representative**  **to Multi-dimensional Images Technology Standardization Forum** | Name : Prof. HyeonWoo Nam  Company: Dongduk Women’s Univ.  Email : [hwnam@dongduk.ac.kr](mailto:hwnam@dongduk.ac.kr) |
| **MOU Representative**  **from IEEE 2888** | Name : Prof. Kyoungro Yoon  Company: Konkuk Univ.  Email : yoonk@konkuk.ac.kr |
| **IEEE's Approval** | To be determined after IEEE internal discussion |
| **Statement of Expected Benefits and Responsibilities** | The MOU will bring an efficiency of communications between the two organizations and contribute to more valid and efficient standard development in terms of defining interfaces of sensors for synchronizing cyber and physical world. Both organizations can give valuable feedbacks to the corresponding organization after reviewing the draft document reflecting efforts of each standardization body. In addition, it is available for members of each group to participate in the standard meetings of the other group as MOUs, and to make more world-wide network.  We believe that there are mutual responsibilities to make collaboration between the two organizations. Each party takes a responsibility to follow the international rules specified in each standard organization. During the standardization, it is necessary to make sure the appropriate procedures for the official processing. |

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| *Dated:* |  | *Dated:* |
| 24-November 2020 |  | 24-November 2020 |
|  |  |  |
| *Signature:* |  | *Signature:* |
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